

Appl. No. 10/672,676
Amdt. dated December 7, 2004
Reply to Office action of October 1, 2004

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1.-31. (Cancelled).

32. (Currently amended) The device of claim ~~[[31]]~~ 33 wherein said means for connecting has a spring constant and said means for damping has a damping value.

33. (Currently amended) A device for minimizing the vibrational motion in a microprocessor connected to a printed wiring board, the device comprising:
means for connecting the microprocessor to the printed wiring board that electrically connects the microprocessor to the printed wiring board,
wherein said means for connecting transmits vibrational motion and allows relative motion between the microprocessor and the printed wiring board; and
means for damping vibrational motion transmitted between the microprocessor and the printed wiring board. ~~The device of claim 31~~
wherein said means for connecting and said means for damping comprise a Kelvin system.

34. (Currently amended) A device for minimizing the vibrational motion in a microprocessor connected to a printed wiring board, the device comprising:
means for connecting the microprocessor to the printed wiring board that electrically connects the microprocessor to the printed wiring board,
wherein said means for connecting transmits vibrational motion and allows relative motion between the microprocessor and the printed wiring board; and

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means for damping vibrational motion transmitted between the microprocessor and the printed wiring board. The device of claim 34
wherein said means for connecting and said means for damping comprise a Maxwell system.

35. (Currently amended) The device of claim [[31]] 33 wherein the device displays a viscoelastic response to applied loads.

36. (Currently amended) The device of claim [[31]] 33 further comprising a heat sink connected to the microprocessor and the printed wiring board by an assembly comprising at least one spring.

37.-45. (Cancelled).

46. (New) The device of claim 33 wherein said means for damping vibrational motion comprises an isolating mount compressed between the microprocessor and the printed wiring board.

47. (New) The device of claim 46 wherein the isolating mount comprises a continuous piece of material that contacts the periphery of the microprocessor.

48. (New) The device of claim 46 wherein said isolating mount comprises a plurality of pieces of material that contact the microprocessor.

49. (New) The device of claim 34 wherein said means for connecting has a spring constant and said means for damping has a damping value.

50. (New) The device of claim 34 wherein the device displays a viscoelastic response to applied loads.

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51. (New) The device of claim 34 further comprising a heat sink connected to the microprocessor and the printed wiring board by an assembly comprising at least one spring.

52. (New) The device of claim 34 wherein said means for damping vibrational motion comprises an isolating mount compressed between the microprocessor and the printed wiring board.

53. (New) The device of claim 52 wherein the isolating mount comprises a continuous piece of material that contacts the periphery of the microprocessor.

54. (New) The device of claim 52 wherein said isolating mount comprises a plurality of pieces of material that contact the microprocessor.